## In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims**

- 1. (currently amended) A wire grid polarizer with double metal layers, comprising: a transparent substrate;
- an array of parallel and elongated dielectric layers protrusions formed on the transparent substrate, wherein the dielectric layers protrusions have a period and a trench is located between adjacent dielectric layers protrusions;
- a first metal layer having a first thickness formed in the trench; and
- a second metal layer having a second thickness and a width formed on each dielectric layer protrusion, wherein the first and second metal layers are separated by a vertical distance;

wherein the period is not greater than 250nm;

wherein the first thickness is not greater than 150nm and is equal to the second thickness; wherein the vertical distance is not greater than 100nm;

wherein the ratio of the width to the period is in a range of 25~75%.

2. (original) The wire grid polarizer according to claim 1, wherein the transparent substrate is exposed in the trench.

- 3. (original) The wire grid polarizer according to claim 1, wherein a remaining dielectric layer is formed on a bottom of the trench.
- 4. (currently amended) The wire grid polarizer according to claim 1, wherein a thickness of the transparent substrate is  $500\sim1500$  [[nm]]  $\mu$ m.
- 5. (original) The wire grid polarizer according to claim 4, wherein the transparent substrate is a glass or plastic substrate.
- 6. (original) The wire grid polarizer according to claim 1, wherein the dielectric layers are PMMA (polymethyl methacrylate) layers.
- 7. (original) The wire grid polarizer according to claim 1, wherein the first metal layer is an Au, Ag, Cu or Al layer.
- 8. (original) The wire grid polarizer according to claim 1, wherein the second metal layer is an Au, Ag, Cu or Al layer.
- 9. (original) The wire grid polarizer according to claim 1, wherein the first and second metal layers comprise the same material.
  - 10. (original) The wire grid polarizer according to claim 1, further comprising: a protective layer formed on the first and second metal layers.

- 11. (original) The wire grid polarizer according to claim 10, wherein the protective layer is a SiO<sub>2</sub>, SiN or SiON layer.
- 12. (original) The wire grid polarizer according to claim 1, wherein the period is in a range of 10~250nm.
- 13. (original) The wire grid polarizer according to claim 1, wherein the first or second thickness is in a range of 30~150nm.
- 14. (original) The wire grid polarizer according to claim 1, wherein the vertical distance is in a range of 10~100nm.
  - 15. (currently amended) A wire grid polarizer with double metal layers, comprising: a transparent substrate;
  - an array of parallel and elongated dielectric layers protrusions formed on the transparent substrate, wherein the dielectric layers protrusions have a period and a trench is located between adjacent dielectric layers protrusions;
  - a first metal layer having a first thickness formed in the trench; and
  - a second metal layer having a second thickness and a width formed on each of the dielectric layers protrusions, wherein a vertical distance is between the first and second metal layers;

wherein the period is in a range of 10~250nm;

wherein the first thickness is in a range of 30~150nm and is equal to the second thickness;

wherein the vertical distance is in a range of 10~100nm;

wherein the ratio of the width to the period is in a range of 25~75%.

- 16. (original) The wire grid polarizer according to claim 15, wherein the transparent substrate is exposed in the trench.
- 17. (original) The wire grid polarizer according to claim 15, wherein a remaining dielectric layer is formed on a bottom of the trench.
- 18. (currently amended) A method of forming a wire grid polarizer with double metal layers, comprising the steps of:

providing a transparent substrate;

forming an array of parallel and elongated dielectric layers protrusions on the transparent substrate, wherein the dielectric layers protrusions have a period and a trench is located between adjacent dielectric layers protrusions;

forming a first metal layer having a first thickness in the trench; and

forming a second metal layer having a second thickness and a width on each dielectric layer protrusion, wherein the first and second metal layers are separated by a vertical distance;

wherein the period is in a range of 10~250nm;

wherein the first thickness is in a range of 30~150nm and is equal to the second thickness;

wherein the vertical distance is in a range of 10~100nm;

wherein the ratio of the width to the period is in a range of 25~75%.

- 19. (original) The method according to claim 18, the transparent substrate is exposed in the trench.
- 20. (original) The method according to claim 18, wherein a remaining dielectric layer is formed on a bottom of the trench.
  - 21. (original) The method according to claim 18, further comprising the step of: forming a protective layer on the first and second metal layers.
- 22. (original) The method according to claim 18, wherein the dielectric layers are formed by photolithography or nanoimprint.